

ASSP For Power Supply Applications

Switching Regulator Controller

MB3776A

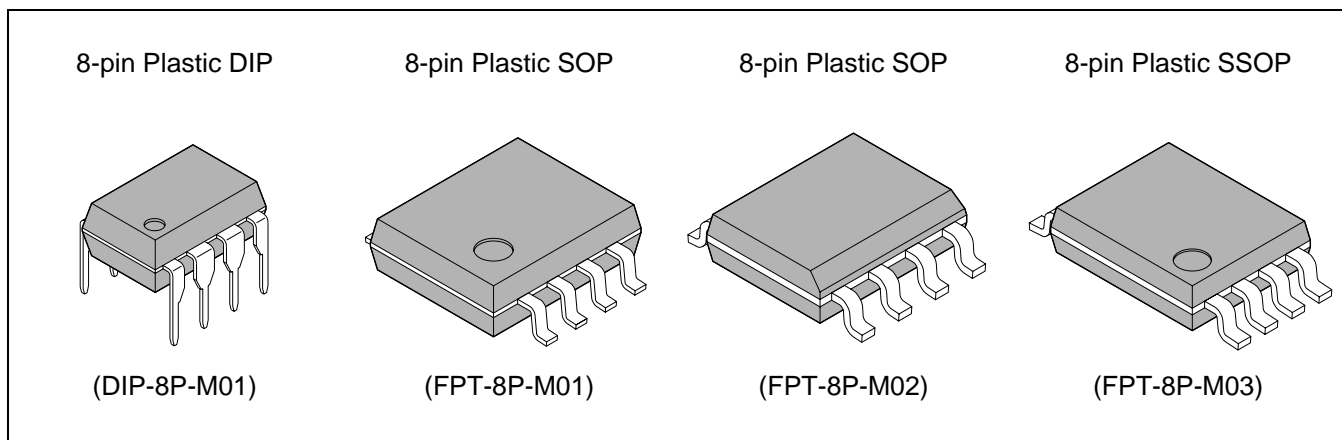
DESCRIPTION

MB3776A is a PWM system switching regulator controller. Because of its low operating supply voltage and power-down, the MB3776A is ideal for use in DC/DC converters for battery-powered portable equipment.

FEATURES

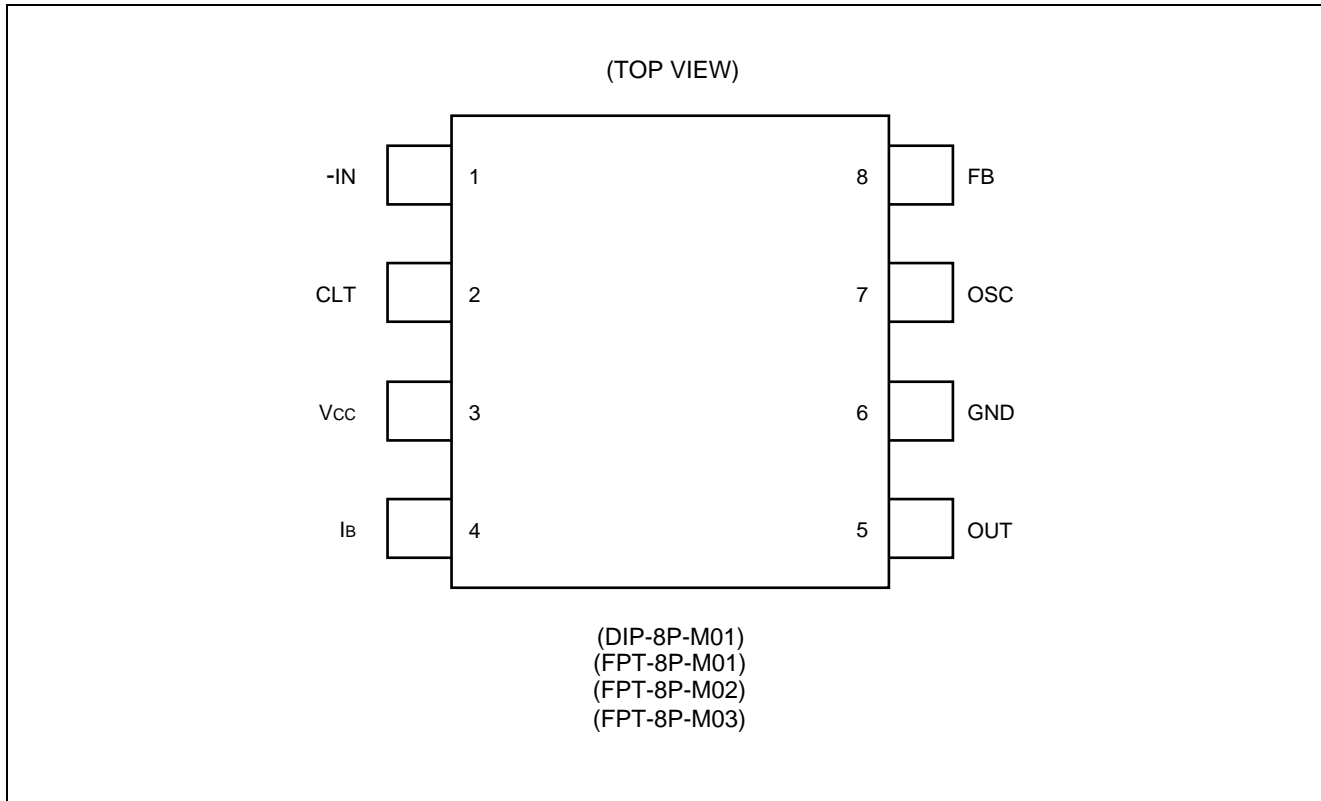
- Wide supply voltage range: (2 V to 15 V)
- Wide oscillation frequency range, high-frequency oscillation: (10 kHz to 500 kHz)
- Push-pull output. Drive current set with external resistor
- Built-in idle period circuit
- Internally set error amplifier gain, few external components
- Built-in power-down function

PACKAGES

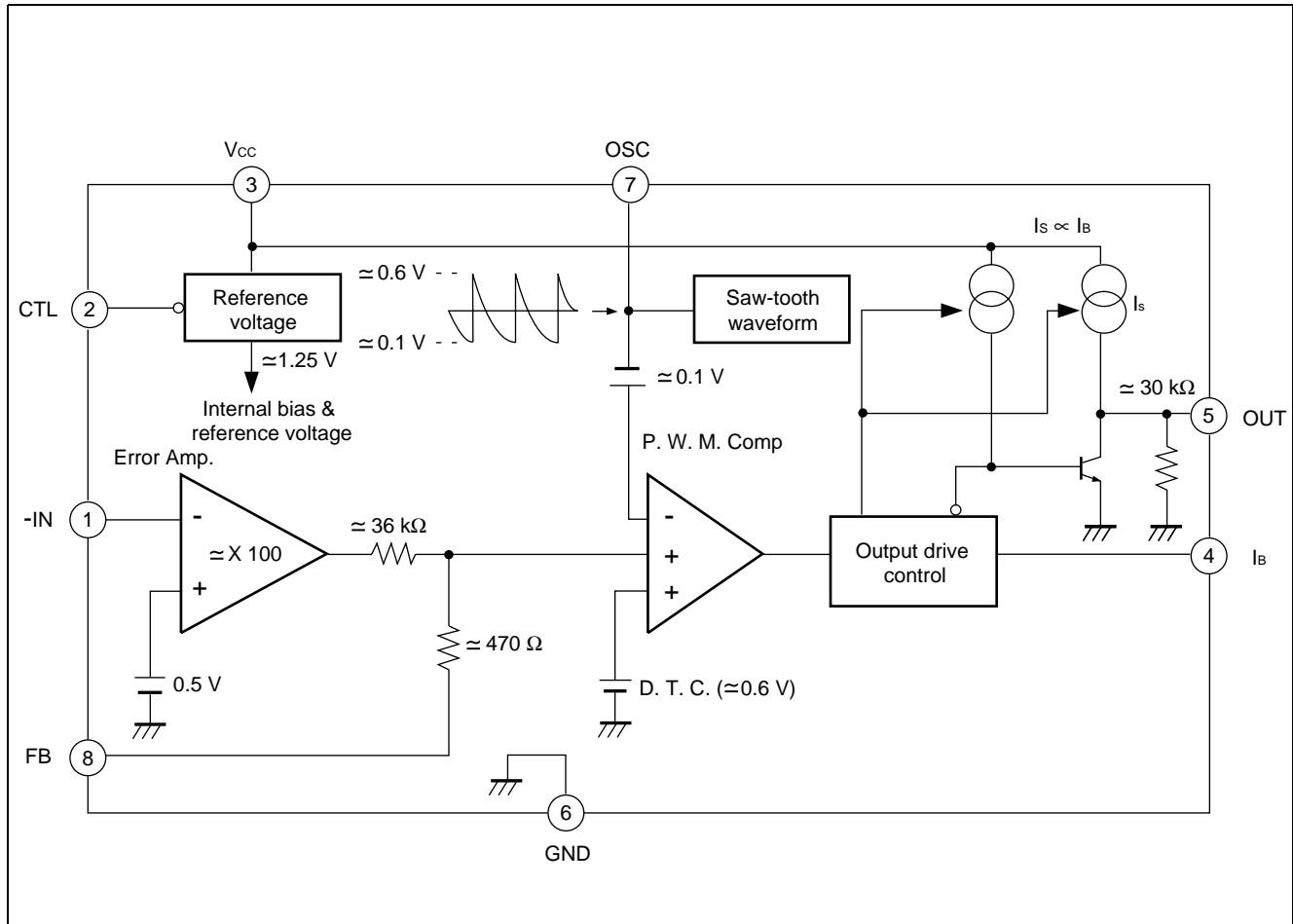


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■ PIN ASSIGNMENT



■ BLOCK DIAGRAM



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■ ABSOLUTE MAXIMUM RATINGS

(Ta = +25°C)

Parameter	Symbol	Condition	Rating		Unit	
			Min	Max		
Power supply voltage	V _{CC}	—	—	16	V	
Error amp. input voltage	V _I	—	-0.3	+10	V	
Output source current	I _{SOURCE}	—	—	-50	mA	
Output sink current	I _{SINK}	—	—	50	mA	
Power dissipation	P _D	Ta ≤ +25°C (DIP)		—	550	mW
		Ta ≤ +25°C (SOP)	EIAJ	—	*570	mW
			JEDEC	—	*430	mW
		Ta < +25°C (SSOP)		—	*580	mW
Operating temperature	T _{OP}	—	-30	+75	°C	
Storage temperature	T _{STG}	—	-55	+125	°C	

*: The packages are mounted on the epoxy board (10 cm × 10 cm × 1.5 mm)

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Power supply voltage	V _{CC}	2.0	—	15	V
Error amp. input voltage	V _I	-0.2	—	1.0	V
Output source current	I _{SOURCE}	-40	—	—	mA
Output sink current	I _{SINK}	—	—	40	mA
Phase compensation capacitor	C _P	—	0.1	—	μF
Timing capacitor	C _T	100	1000	10000	pF
Timing resistor	R _T	1.0	3.0	5.0	kΩ
Oscillator frequency	f _{OSC}	10	200	500	kHz
Operating temperature	T _{OP}	-30	25	75	°C

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

1. Reference Section and Error Amp. Section

($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Input threshold voltage	V_T	$V_{FB} = 450\text{ mV}$	487	507	527	mV
V_T input stability	V_{TdV1}	$V_{CC} = 2.0\text{ V to }6.0\text{ V}$	-5	—	5	mV
	V_{TdV2}	$V_{CC} = 6.0\text{ V to }15\text{ V}$	-5	—	5	mV
V_T temp. stability	V_{TdT}	$T_a = -30^\circ\text{C to }+75^\circ\text{C}$	-3	—	3	%
Input bias current	I_B	$V_{IN} = 0\text{ V to }0.6\text{ V}$	-1.0	-0.2	1.0	μA
Voltage gain	A_v	—	70	100	145	V/V
Frequency band width	BW	$A_v = 0\text{ dB}$	—	6	—	MHz

2. Saw-tooth Waveform Oscillator Section

($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Oscillator frequency	f_{OSC}	$R_T = 3.0\text{ k}\Omega$ $C_T = 1000\text{ pF}$	160	200	240	kHz
Frequency input stability	f_{dV}	$V_{CC} = 2.0\text{ V to }15\text{ V}$	—	± 2	—	%
Frequency temp. stability	f_{dT}	$T_a = -30^\circ\text{C to }+75^\circ\text{C}$	—	± 10	—	%

3. Under Lockout Protection

($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Threshold voltage	V_{TH}	—	—	1.4	—	V

4. Dead-time Control Section

($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Max duty cycle	t_{DUTY}	$C_T = 1000\text{ pF}$ $R_T = 3.0\text{ k}\Omega$ $V_{FB} = 0.9\text{ V}$	60	70	85	%

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5. Output Section

($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Output source current	I_{SOURCE}	$R_B = 820\ \Omega$, $V_O = 1\text{ V}$	-40	-30	-20	mA
Output sink current	I_{SINK}	$R_B = 820\ \Omega$, $V_O = 0.3\text{ V}$	30	60	—	mA
High-level output voltage	V_{OH}	$R_B = 820\ \Omega$, $V_O = 7\text{ V}$ $I_O = -15\text{ mA}$	5.5	6.0	—	V
Output voltage	V_{OL}	$V_{CTL} = V_{CC}$, $I_O = 3\ \mu\text{A}$	—	0.1	0.2	V

6. Control Section

($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

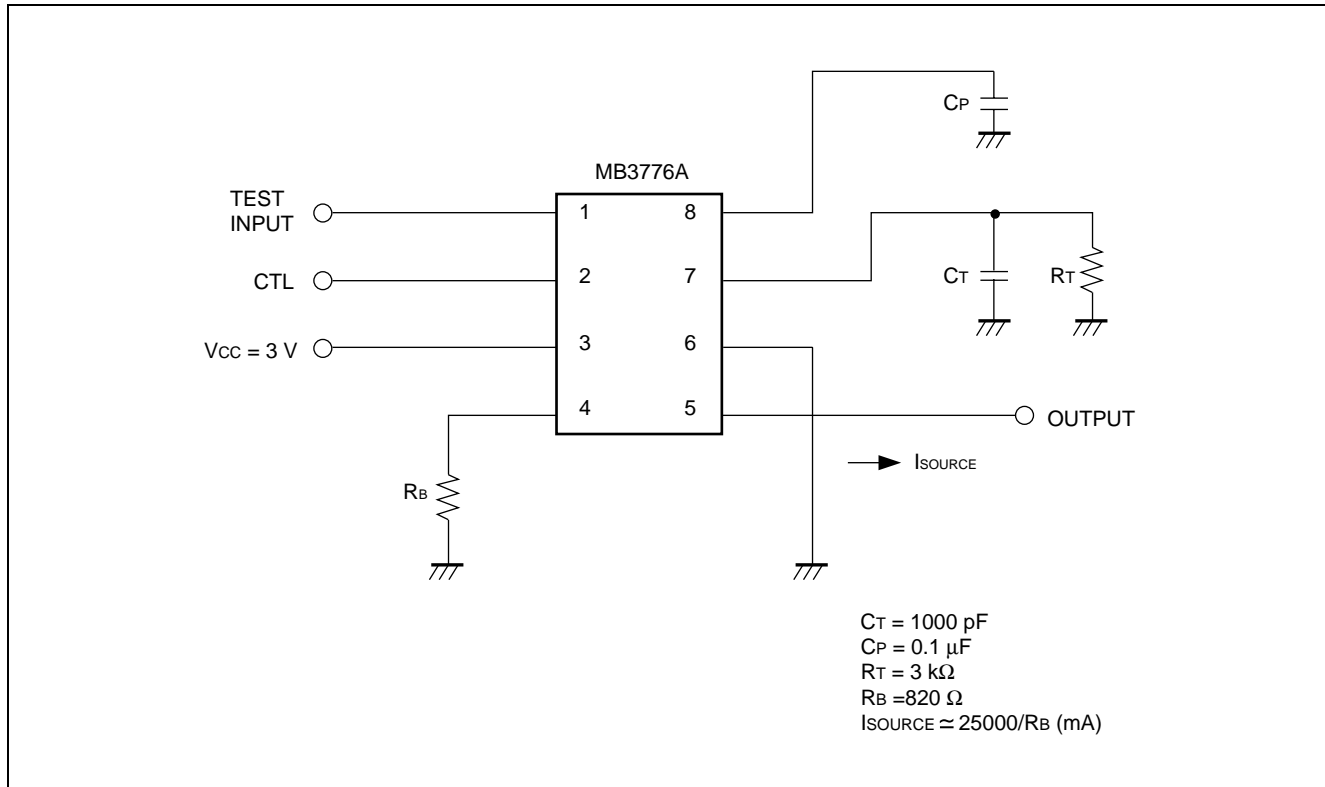
Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Input off condition	I_{OFF}	—	-300	—	—	μA
Input on condition	I_{ON}	—	—	—	-700	μA
Control terminal current	I_{CTL}	$V_{CC} = 7\text{ V}$, $V_{CTL} = 0\text{ V}$	-1.3	-1	—	mA

7. All Device

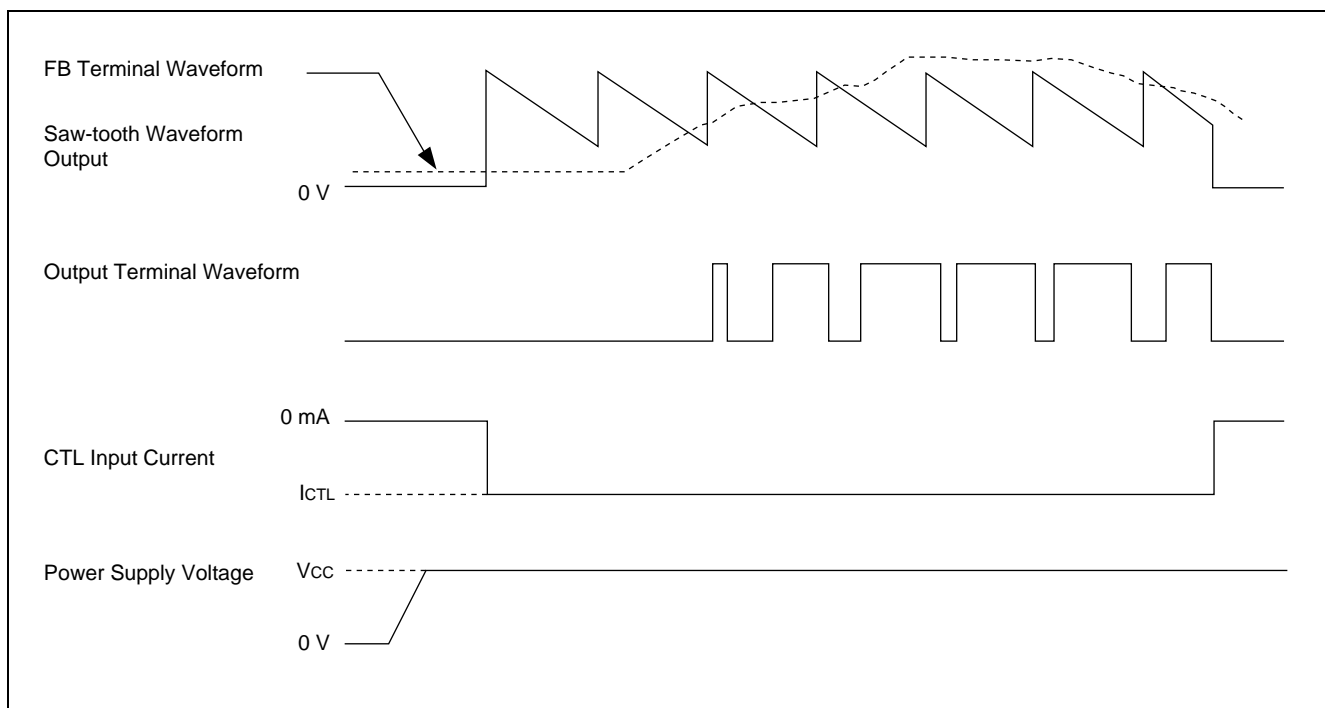
($T_a = +25^\circ\text{C}$, $V_{CC} = 3\text{ V}$)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Stand by current	I_{CCS}	$V_{CTL} = V_{CC}$ OR CTL terminal open	—	—	0.5	μA
Average supply current	I_{CC}	$I_{CTL} = -700\ \mu\text{A}$ $R_B = 820\ \Omega$	—	4.5	8	mA

MEASUREMENT CIRCUIT

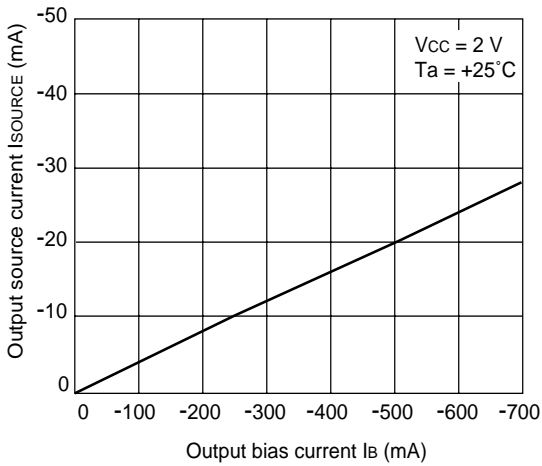


DIAGRAM

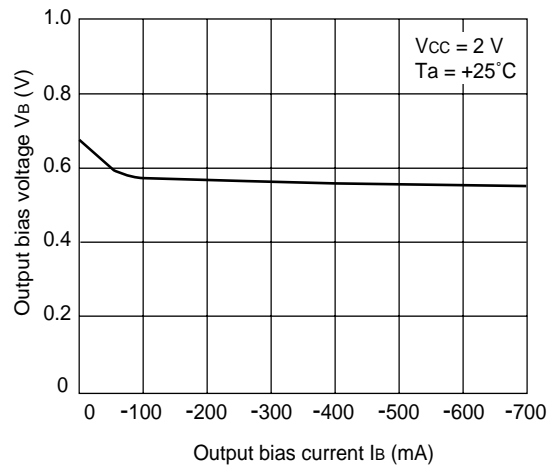


TYPICAL CHARACTERISTIC

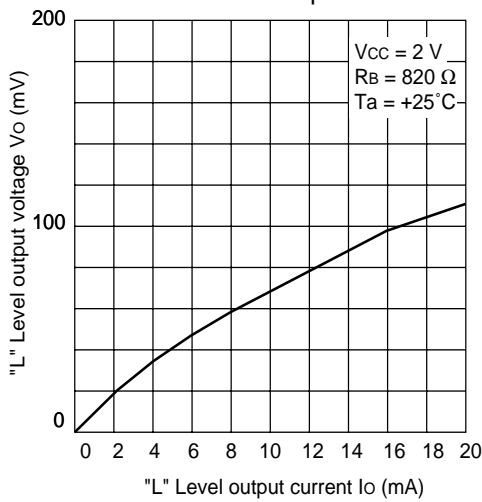
Output bias current vs. Output source current



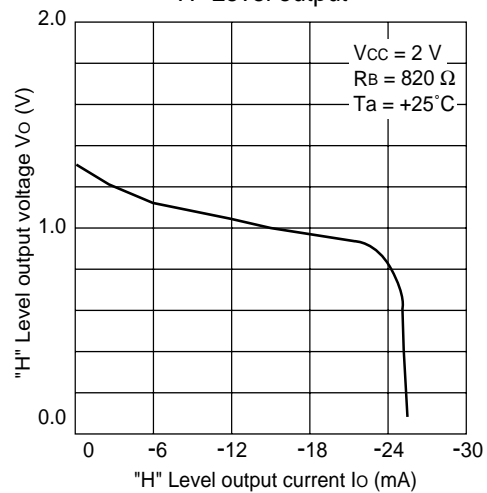
Output bias current vs. Output bias voltage



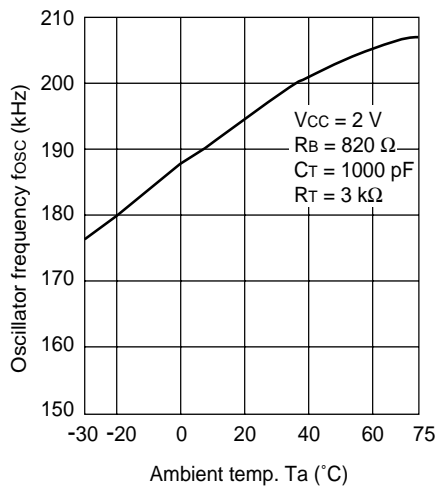
"L" Level output



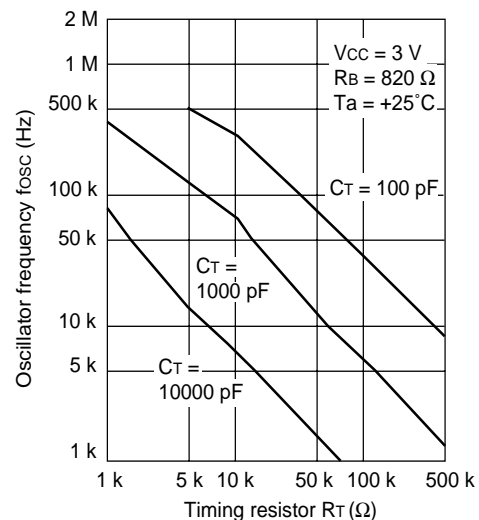
"H" Level output



Ambient temp. vs. Oscillator frequency



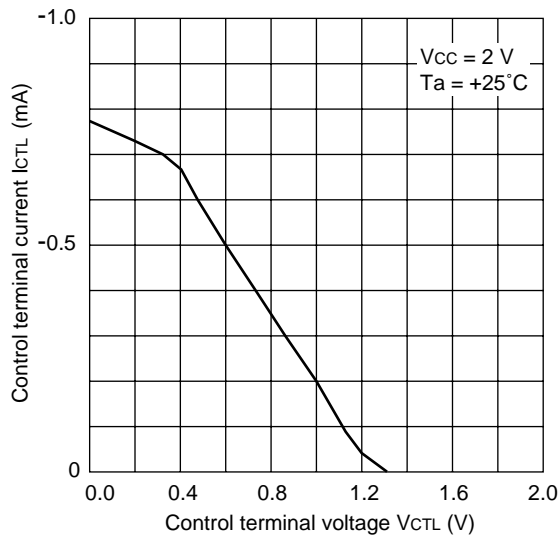
Timing resistor vs. Oscillator frequency



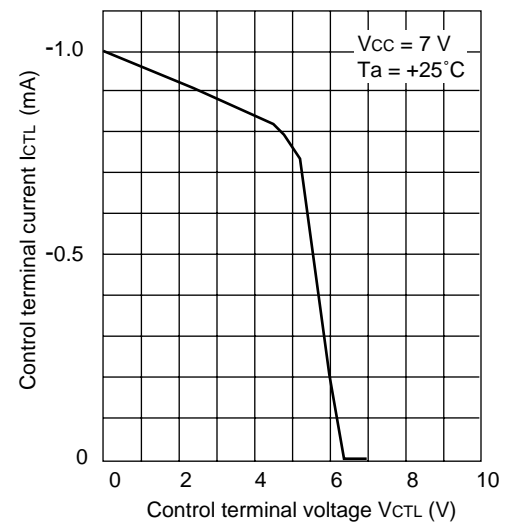
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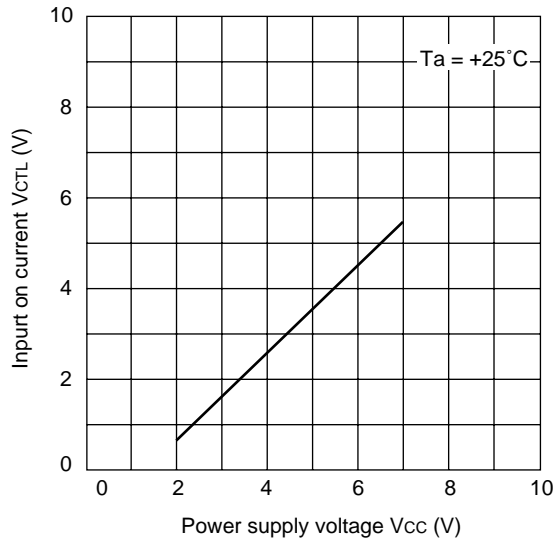
Control terminal voltage vs.
Control terminal current



Control terminal voltage vs.
Control terminal current

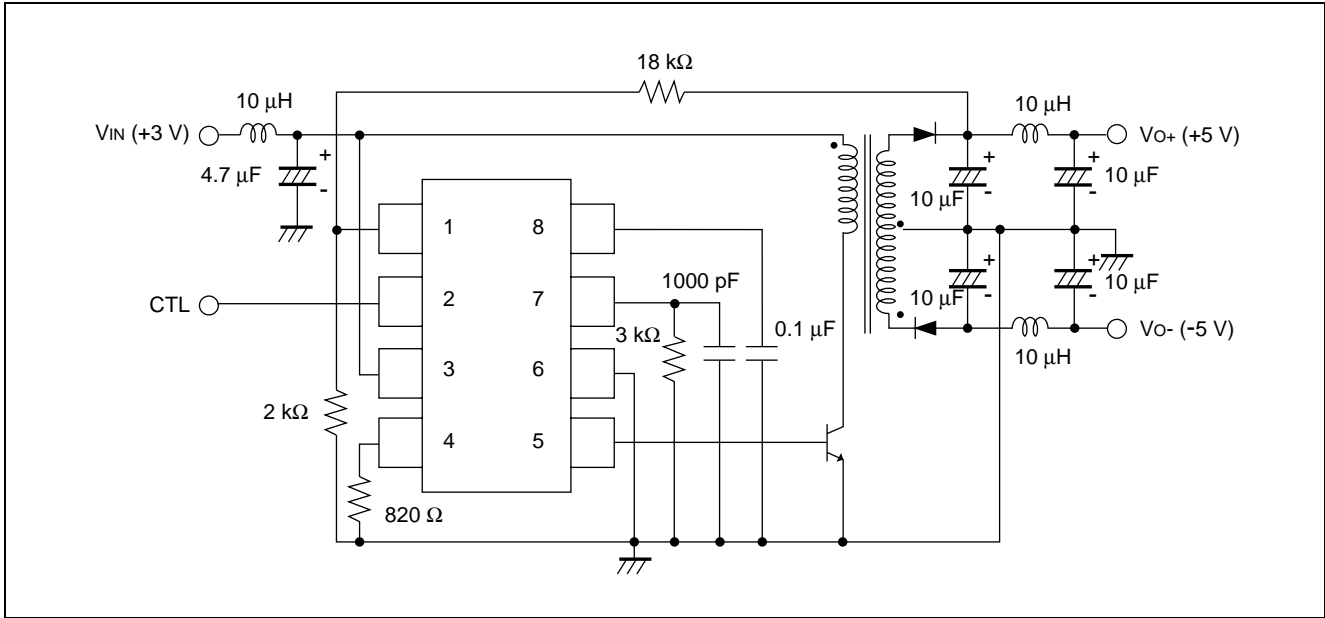


Power supply voltage vs. Input on voltage



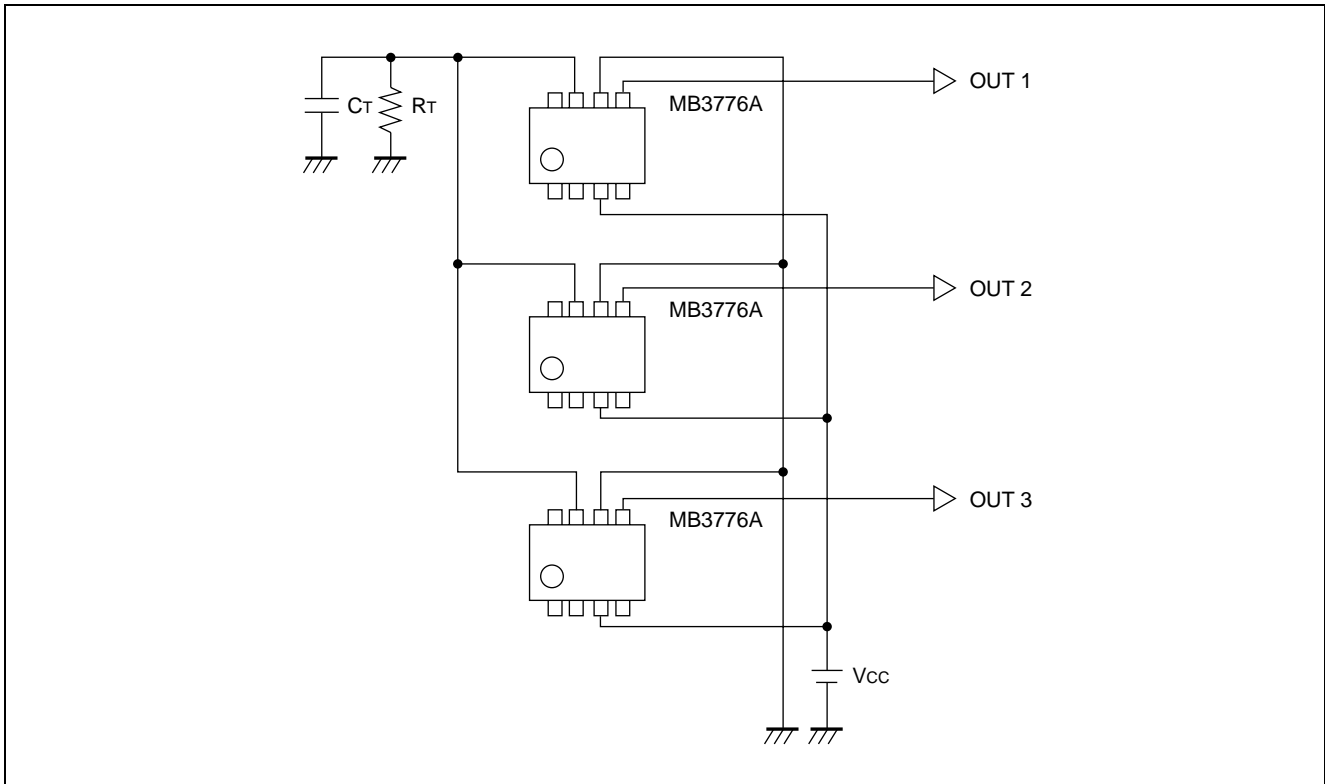
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APPLICATION EXAMPLE



Synchronization

To synchronize MB3776A controllers, the OSC terminal of each IC is shared and the same specified capacitor and resistor used on a signal IC application is connected for self-excitation oscillation. The CTL terminal controls power on/off of each IC.



■ NOTES ON USE

- Take account of common impedance when designing the earth line on a printed wiring board.
- Take measures against static electricity.
 - For semiconductors, use antistatic or conductive containers.
 - When storing or carrying a printed circuit board after chip mounting, put it in a conductive bag or container.
 - The work table, tools and measuring instruments must be grounded.
 - The worker must put on a grounding device containing 250 k Ω to 1 M Ω resistors in series.
- Do not apply a negative voltage
 - Applying a negative voltage of -0.3 V or less to an LSI may generate a parasitic transistor, resulting in malfunction.

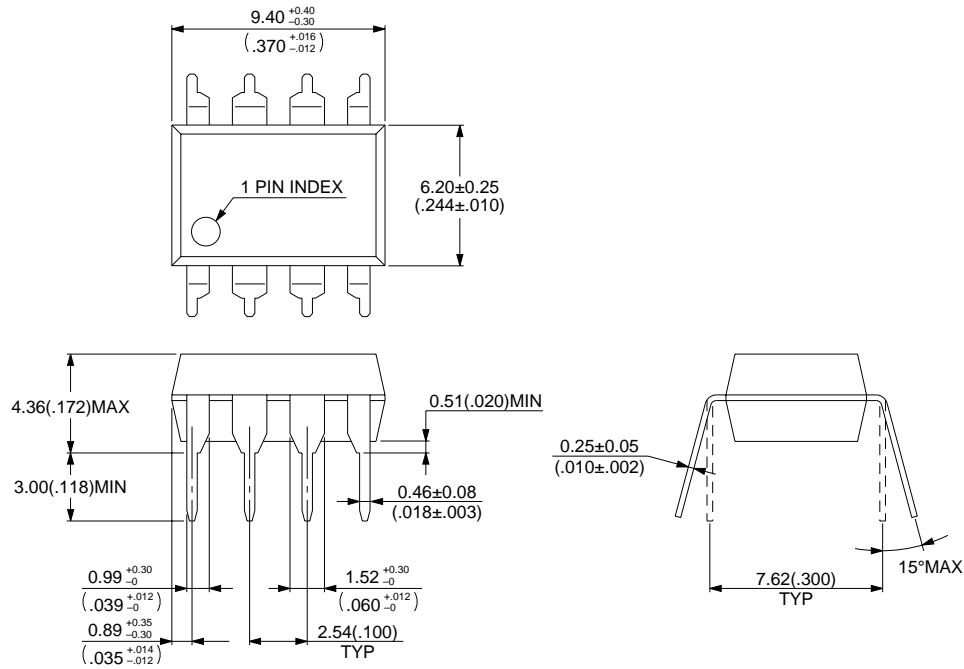
■ ORDERING INFORMATION

Part number	Package	Remarks
MB3776A-P	8-pin Plastic DIP (DIP-8P-M01)	
MB3776APF	8-pin Plastic SOP (FPT-8P-M01)	
MB3776APNF	8-pin Plastic SOP (FPT-8P-M02)	
MB3776APFV	8-pin Plastic SSOP (FPT-8P-M03)	

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■ PACKAGE DIMENSIONS

8-pin Plastic DIP
(DIP-8P-M01)



Dimensions in mm (inches) .

Note : The values in parentheses are reference values.

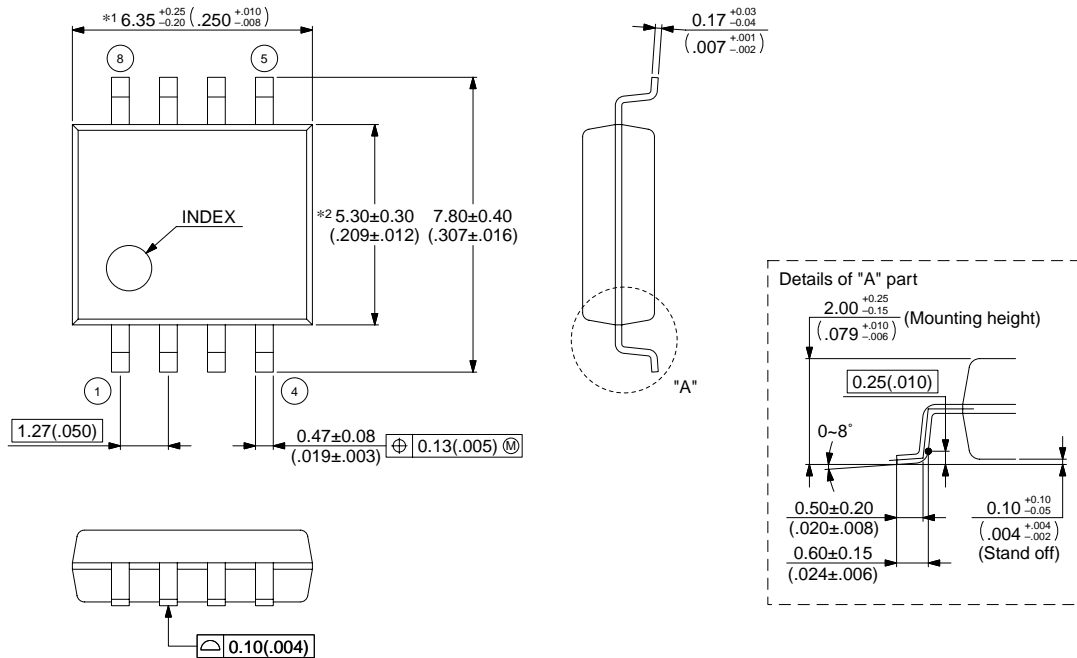
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8-pin Plastic SOP (FPT-8P-M01)

- Note 1) *1 : These dimensions include resin protrusion.
 Note 2) *2 : These dimensions do not include resin protrusion.
 Note 3) Pins width and pins thickness include plating thickness.
 Note 4) Pins width do not include tie bar cutting remainder.



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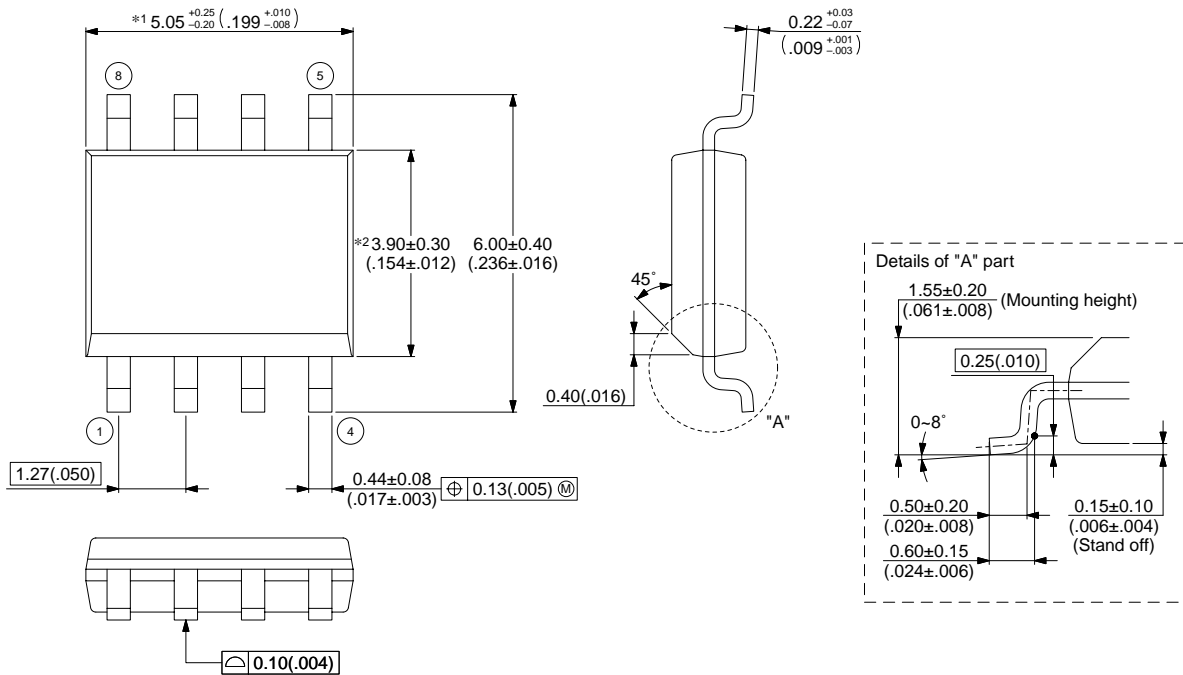
Dimensions in mm (inches) .
 Note : The values in parentheses are reference values.

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MB3776A

8-pin Plastic SOP (FPT-8P-M02)

- Note 1) *1 : These dimensions include resin protrusion.
 Note 2) *2 : These dimensions do not include resin protrusion.
 Note 3) Pins width and pins thickness include plating thickness.
 Note 4) Pins width do not include tie bar cutting remainder.



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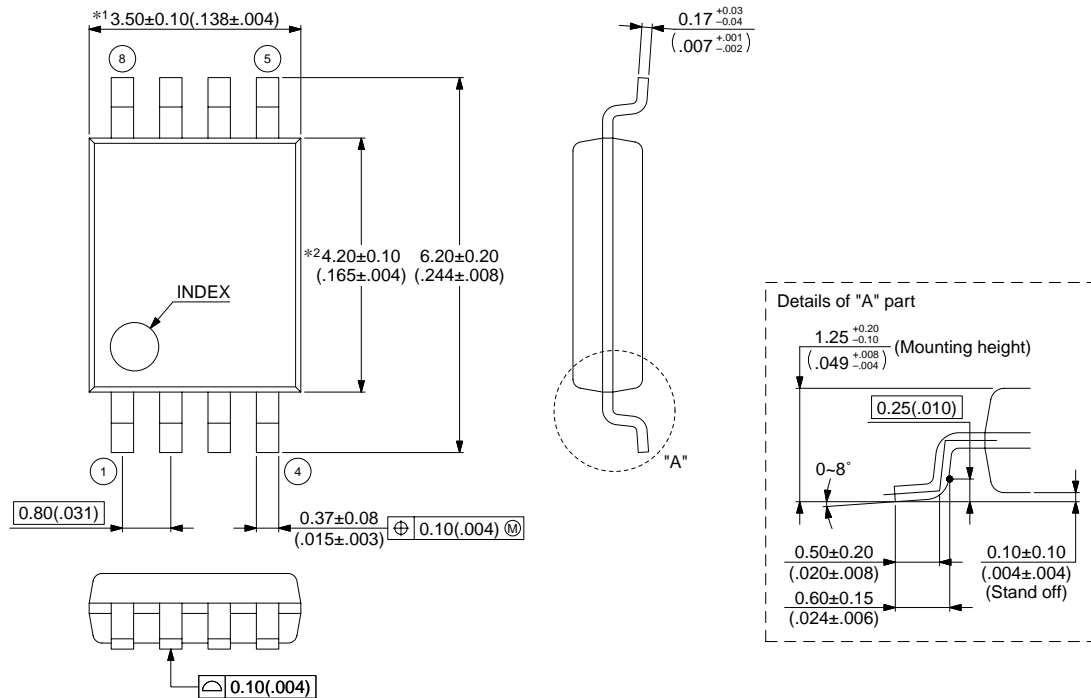
Dimensions in mm (inches) .
 Note : The values in parentheses are reference values.

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8-pin Plastic SSOP (FPT-8P-M03)

- Note 1) *1 : These dimensions include resin protrusion.
 Note 2) *2 : These dimensions do not include resin protrusion.
 Note 3) Pins width and pins thickness include plating thickness.
 Note 4) Pins width do not include tie bar cutting remainder.



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Dimensions in mm (inches) .
 Note : The values in parentheses are reference values.

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